



ORIENT

Photo coupler

Product Data Sheet

MPN: ORPC-851 series

Customer: _____

Date: _____

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Preliminary

This datasheet is a preliminary design specification, and the formal specifications are subject to the recognition letter with jointly signed

1. Features

- (1) High Collector- Emitter Voltage ($V_{CEO} = 350V$)
- (2) Current transfer ratio(CTR: 50~600% at $I_F = 5mA$, $V_{CE} = 5V$)
- (3) High isolation voltage between input and output ($V_{iso} = 5000 V_{rms}$)
- (4) Pb free and RoHS compliant.
- (5) In compliance with RoHS, REACH standards
- (6) MSL Class I
- (7) Safety approval

UL approved (No.E323844)

VDE approved (No.40029733)

CQC approved (No.CQC09001029446)



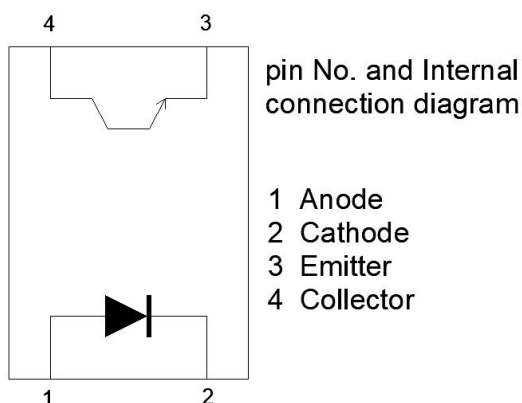
2. Description

- (1) The ORPC-851 series devices consist an infrared emitting diodes, optically coupled to a photo transistor detector.
- (2)The devices are in a 4-pin DIP package and available in wide-lead spacing and SMD option.

3. Applications

- (1) Telephone line interface
- (2) Interface to power supply circuit
- (3) Controller for SSRs. DC motor
- (4) Programmable Controllers

4. Functional Diagram



5. Absolute Maximum Ratings at Ta=25°C

Parameter		Symbol	Rated Value	Unit
Input	Forward Current	I_F	60	mA
	Peak forward Current (100μs pulse, 100Hz frequency)	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	100	mW
Output	Collector and Emitter Voltage	V_{CEO}	350	V
	Emitter and Collector Voltage	V_{ECO}	7	
	Collector Current	I_C	50	mA
	Consume Power	P_C	150	mW
Total Power Dissipation		P_{tot}	200	mW
*1 Isolation Voltage		V_{iso}	5,000	Vrms
Operating Temperature		T_{opr}	-55 to + 100	°C
Storage Temperature		T_{stg}	-55 to + 125	
*2 Soldering Temperature		T_{sol}	260	

1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.

2. For 10 Seconds

6. Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Parameter		Symbol	Min	Typ.*	Max	Unit	Condition
Input	Forward Voltage	V_F	---	1.2	1.4	V	$I_F=10\text{mA}$
	Reverse Current	I_R	---	---	5	μA	$V_R=5\text{V}$
	Collector capacitance	C_t	---	30	250	pF	$V=0, f=1\text{KHz}$
Output	Collector to emitter Current	I_{CEO}	---	---	100	nA	$V_{CE}=200\text{V}, I_F=0\text{mA}$
	Collector and Emitter Breakdown Voltage	BV_{CEO}	350	---	---	V	$I_C=0.1\text{mA}, I_F=0\text{mA}$
	Emitter and Collector Breakdown Voltage	BV_{ECO}	7	---	---	V	$I_E=0.1\text{mA}, I_F=0\text{mA}$
Transforming Characteristics	*1 Current conversion ratio	CTR	50	---	600	%	$I_F=5\text{mA}, V_{CE}=5\text{V}$
	Collector Current	I_C	2.5	---	30	mA	
	Collector and Emitter Saturation Voltage	$V_{CE(sat)}$	---	0.1	0.3	V	$I_F=20\text{mA}, I_C=1\text{mA}$
	Insulation Impedance	R_{iso}	5×10^{10}	1×10^{12}	---	Ω	DC500V 40~60%R.H.
	Floating Capacitance	C_f	---	0.6	1.0	pF	$V=0, f=1\text{MHz}$
	Cut-off Frequency	f_c	---	50	---	kHz	$V_{CE}=5\text{V}, I_C=2\text{mA}, R_L=100\Omega, -3\text{dB}$
	Rise Time	t_r	---	4	10	μs	$V_{CE}=2\text{V}, I_C=2\text{mA}, R_L=100\Omega$
	Fall Time	t_f	---	5	12	μs	

*1 Current Conversion Ratio = $I_C / I_F \times 100\%$, CTR Tolerance: $\pm 3\%$.

7. Order Information

Part Number

ORPC-851X-V-W-Y-Z

Note

X = Lead form option (S, M or none)

V = Tape and reel option (TP, TP1 or none).

W = Lead frame option (F: Iron, C: copper)

Y = 'V' code for VDE safety (This option is not necessary).

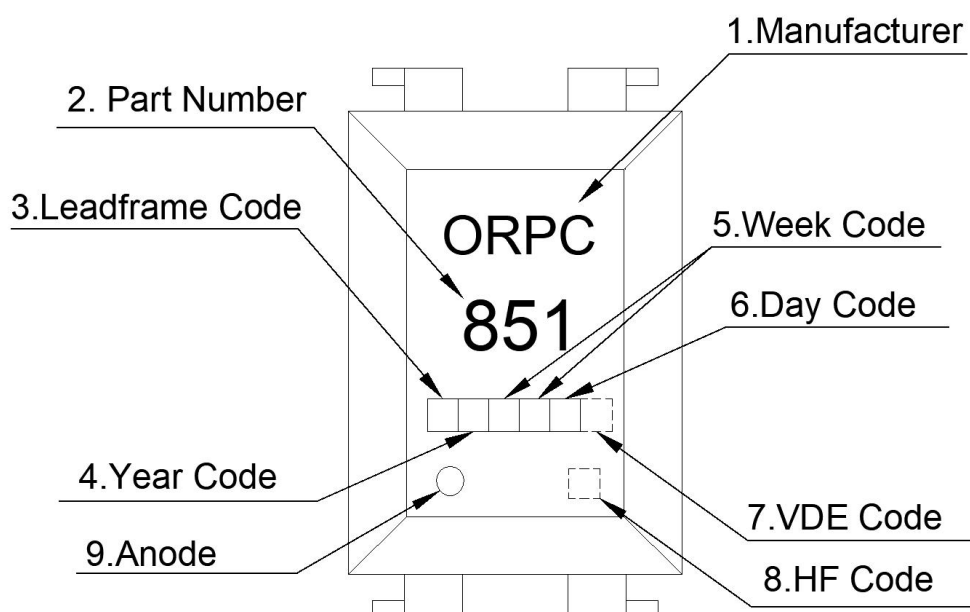
Z = 'G' code for Halogen free. (This option is not necessary).

* Halogen Free can be selected.

* VDE Code can be selected.

Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S(TP)	Surface mount lead form (low profile) + TP tape & reel option	2000 units per reel
S(TP1)	Surface mount lead form (low profile) + TP1 tape & reel option	2000 units per reel

8. Naming Rule



(1) Manufacturer : ORIENT.

(2) 851 denotes Part Number.

(3) Lead frame Code : 'F' means Iron, 'C' means Copper.

(4) Year Code : '1' means '2021' and so on.

(5) Week Code : 01 means the first week, 02 means the second week and so on.

(6) Day Code : "A to G" means "Monday to Sunday"

(7) VDE Code . (Optional)

(8) HF Code : Halogen Free. (Optional)

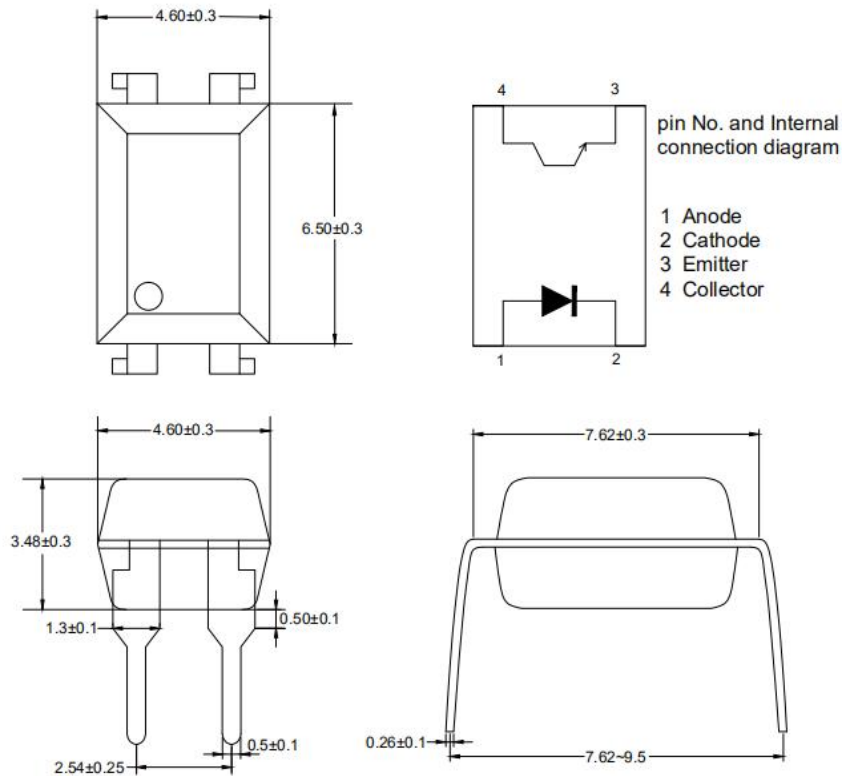
(9) Anode.

* Halogen Free Mark can be selected.

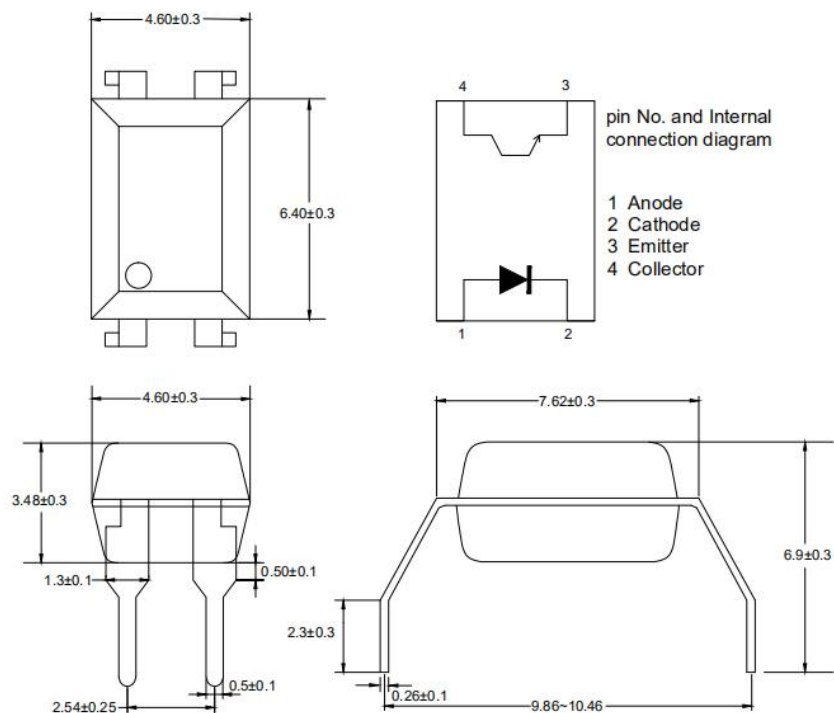
* VDE Mark can be selected.

9. Package Dimension (Unit: mm)

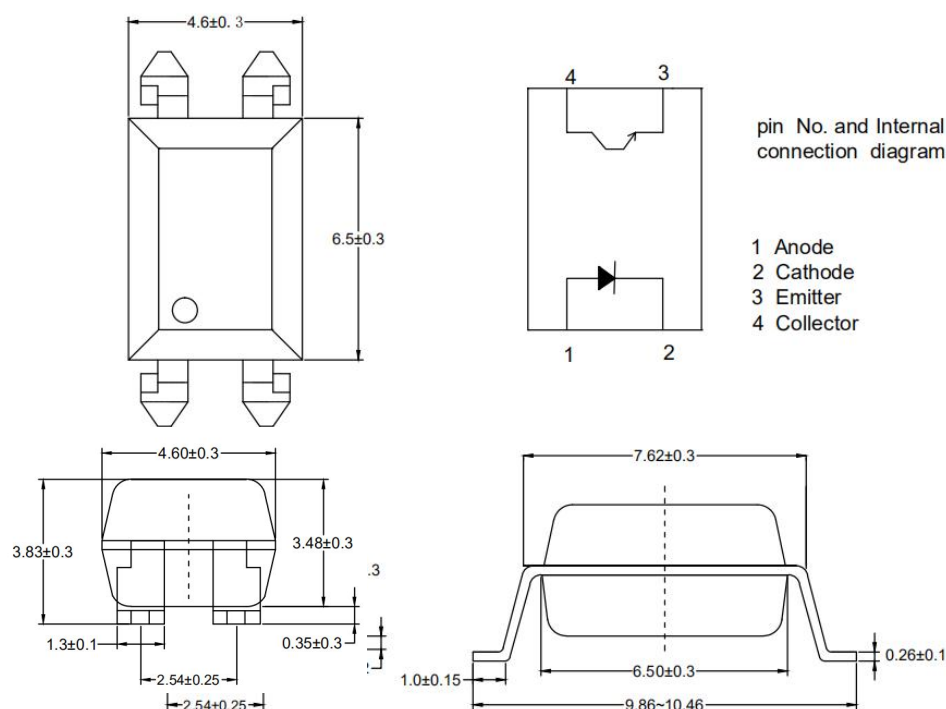
1. ORPC-851



2. ORPC-851M

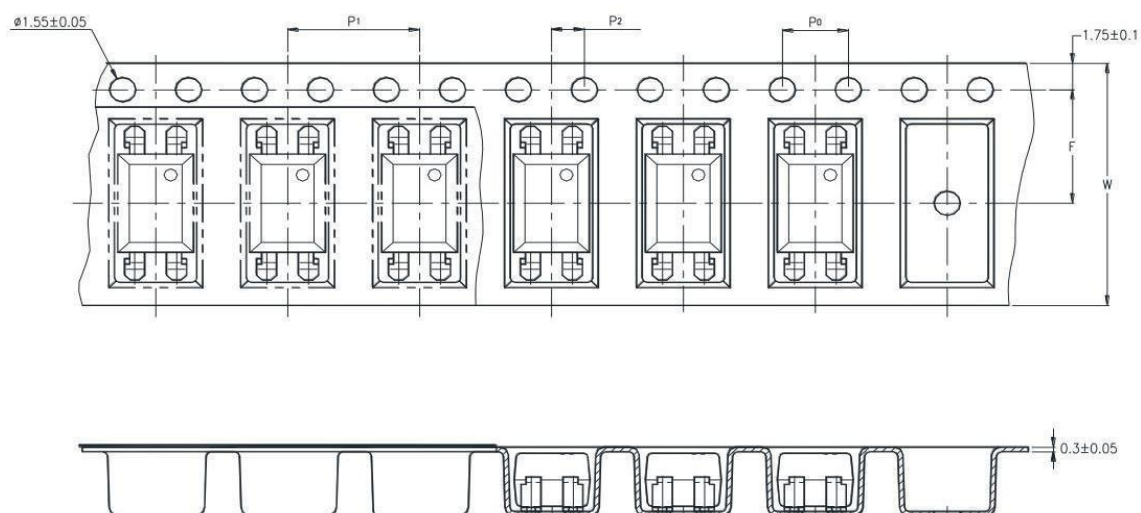


3. ORPC-851S

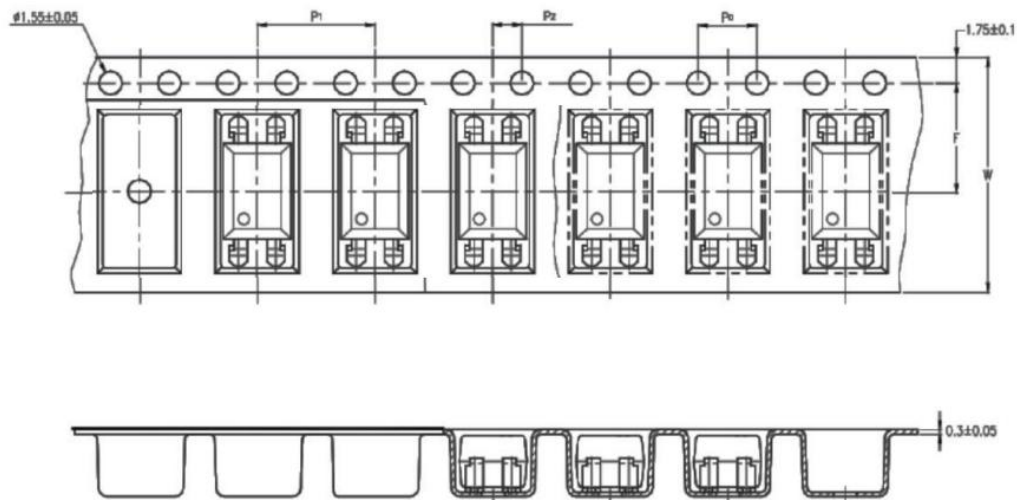


10. Taping Dimensions

(1)ORPC-851S-TP



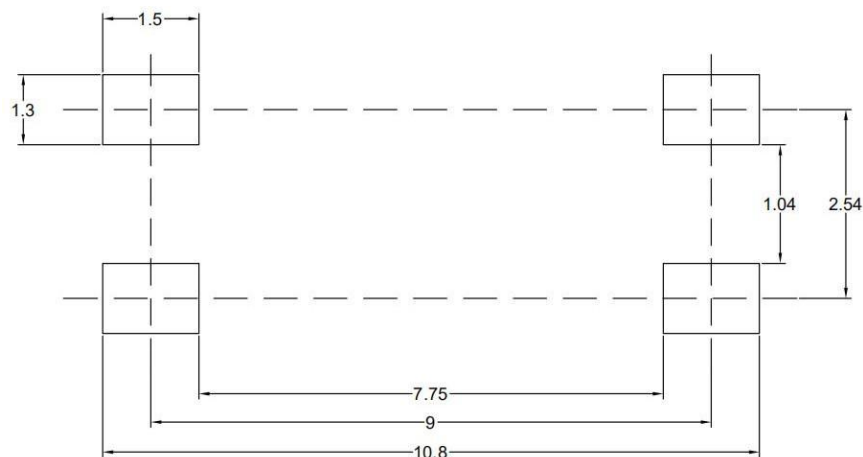
(2)ORPC-851S-TP1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (.63)
Pitch of sprocket holes	P ₀	4±0.1 (.15)
Distance of compartment	F	7.5±0.1 (.295)
	P ₂	2±0.1 (.0079)
Distance of compartment to compartment	P ₁	8±0.1 (.472)

Package Type	TP/TP1
Quantities(pcs)	2000

11. Recommended Foot Print Patterns (Mount Pad) (Unit: mm)



12. Package Dimension

(1) package dimension

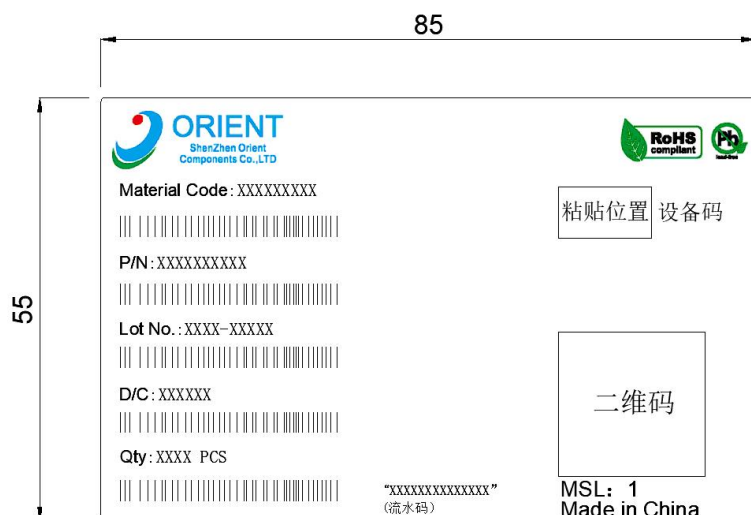
DIP Type

Packing Information	
Packing type	Tube
Qty per Tube	100pcs
Small box (Inner) Dimension	525*128*60mm
Large box (Outer) Dimension	545*290*335mm
The Amount per Inner Box	5,000pcs
The Amount per Outer Box	50,000pcs

SOP Type

Packing Information	
Packing type	Reel type
Tape Width	16mm
Qty per Reel	2,000pcs
Small box (inner) Dimension	345*345*58.5mm
Large box (Outer) Dimension	620x360x360mm
Max qty per small box	4,000pcs
Max qty per large box	40,000pcs

(2)Packing Label Sample



Note:

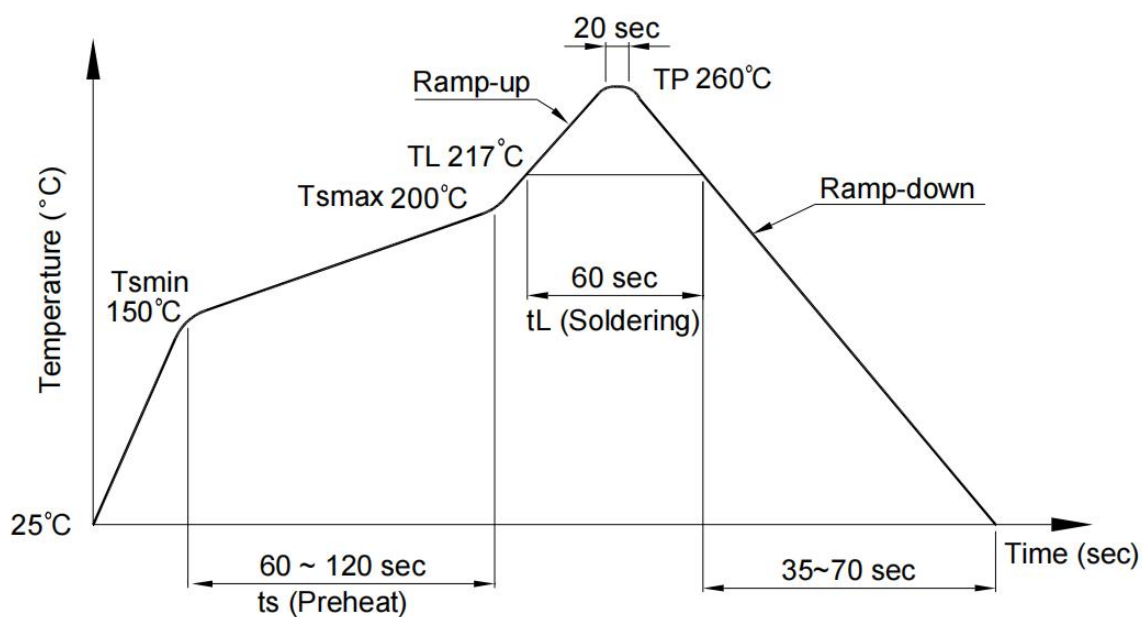
1. Material Code :Product ID.
2. P/N :Contents with "Order Information" in the specification.
3. Lot No. :Product weeks.
4. D/C :Product data.
5. Quantity :Packaging quantity.

13. Temperature Profile Of Soldering

(1).IR Reflow soldering (JEDEC-STD-020 compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

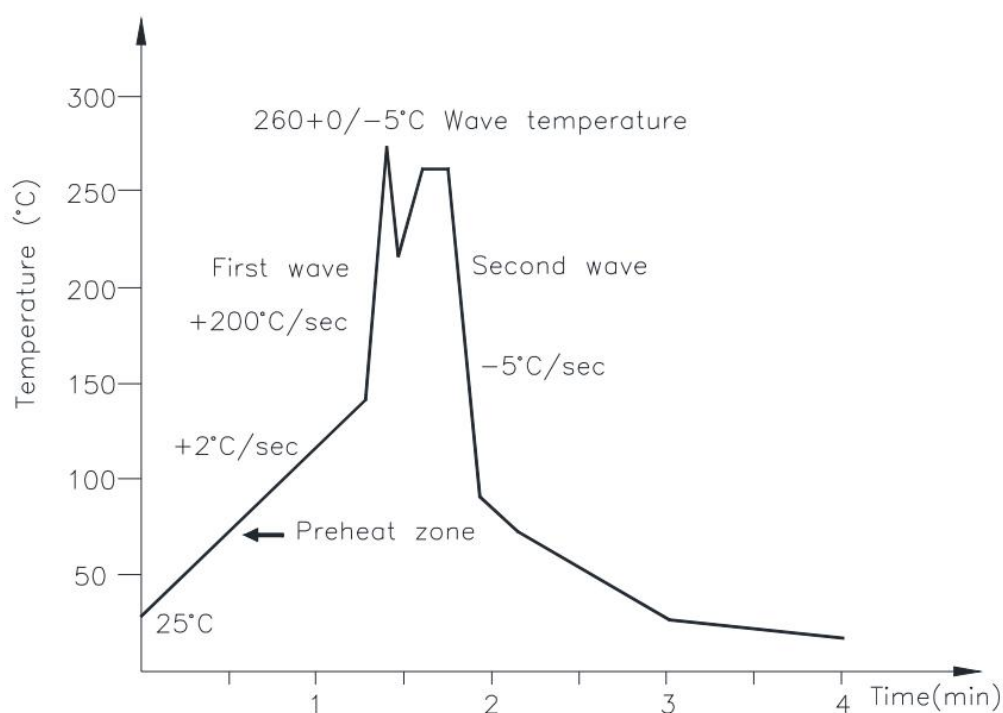
Profile item	Conditions
Preheat	
- Temperature Min (T Smin)	150°C
- Temperature Max (T Smax)	200°C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (TL)	217°C
- Time (t L)	60 sec
Peak Temperature	260°C
Peak Temperature time	20 sec
Ramp-up rate	3°C / sec max.
Ramp-down rate from peak temperature	3~6°C / sec
Reflow times	≤3



(2).Wave soldering (JEDEC22 A111 compliant)

One time soldering is recommended within the condition of temperature.

Temperature	260+0/-5°C
Time	10 sec
Preheat temperature	25 to 140°C
Preheat time	30 to 80 sec



(3).Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature	380+0/-5°C
Time	3 sec max

14. Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

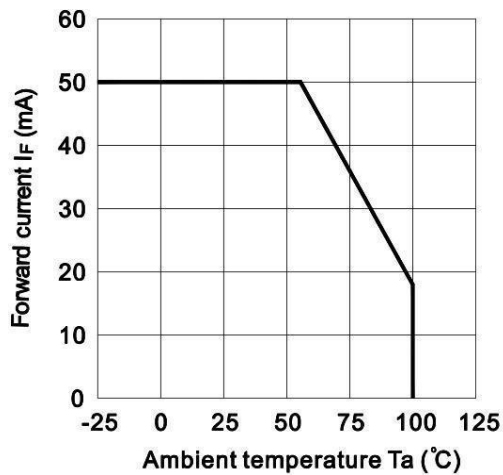


Fig.2 Collector Power Dissipation vs. Ambient Temperature

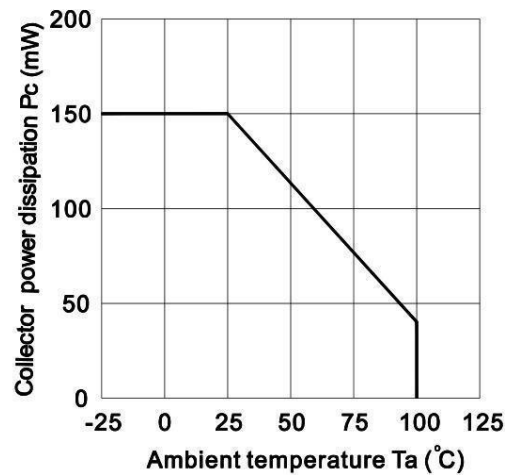


Fig.3 Collector-emitter saturation Voltage vs. Forward current

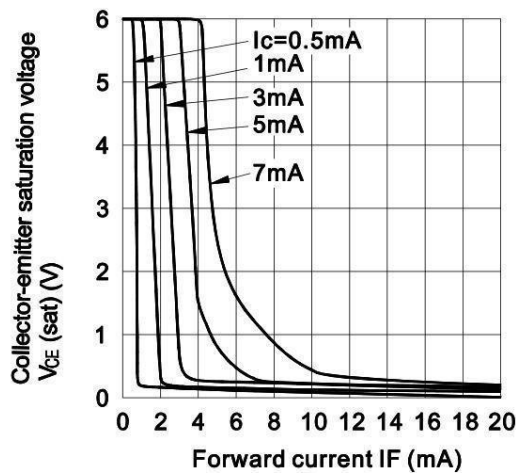


Fig.4 Forward Current vs. Forward Voltage

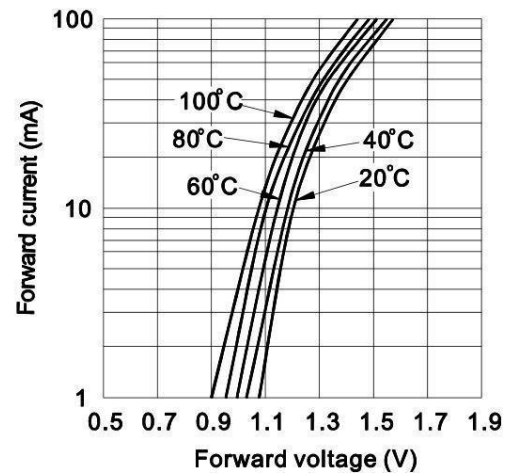


Fig.5 Current Transfer Ratio vs. Forward Current

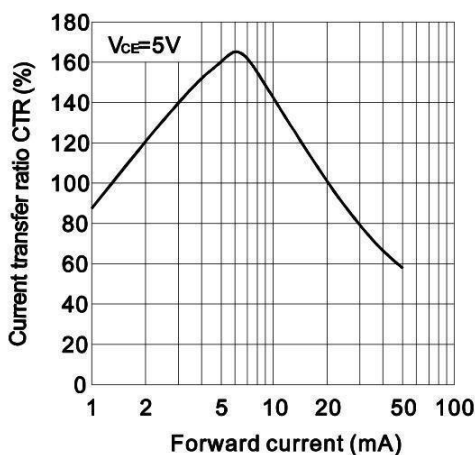


Fig.6 Collector Current vs. Collector-emitter Voltage

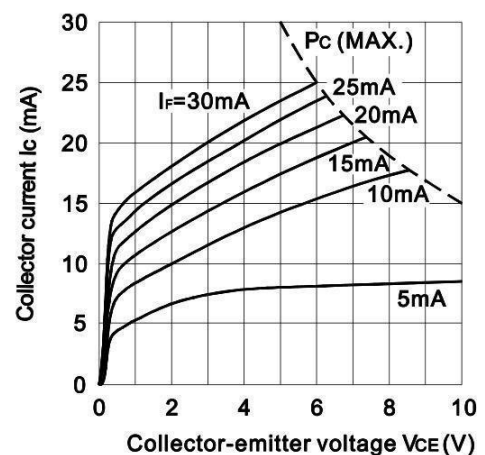


Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

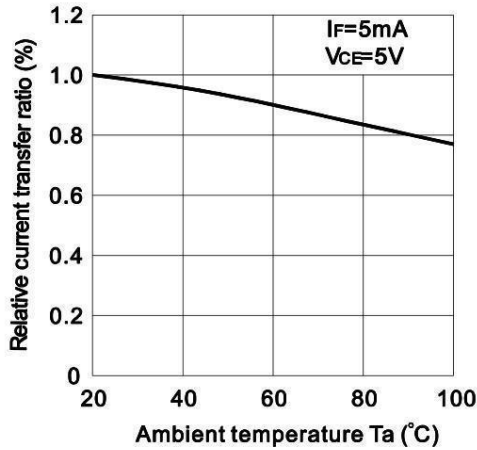


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

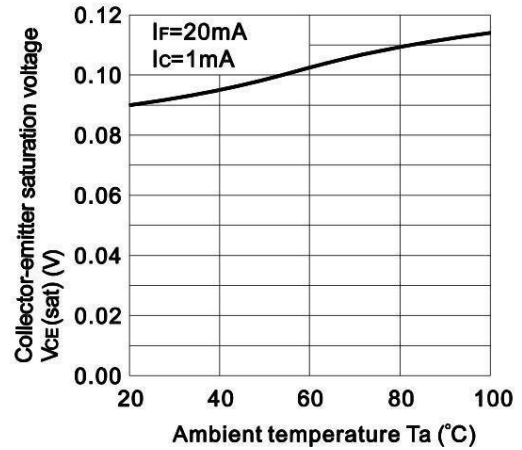


Fig.9 Collector Dark Current vs. Ambient Temperature

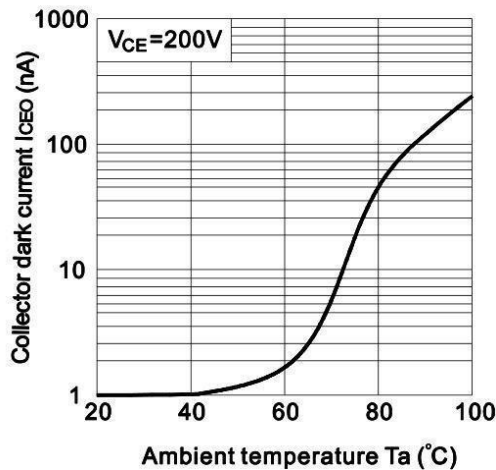


Fig.10 Response Time vs. Load Resistance

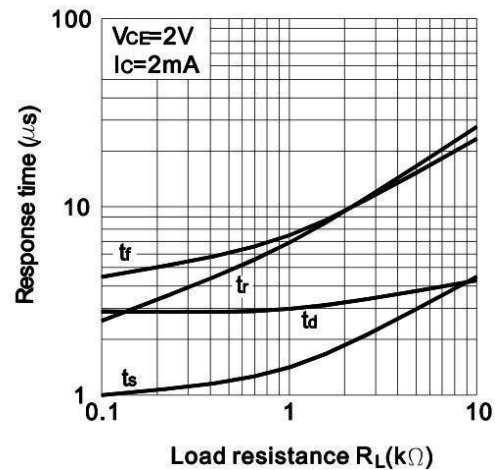
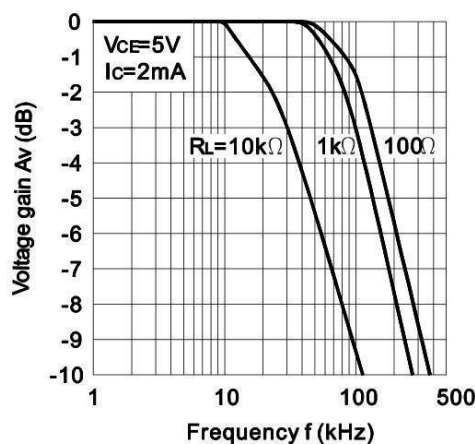
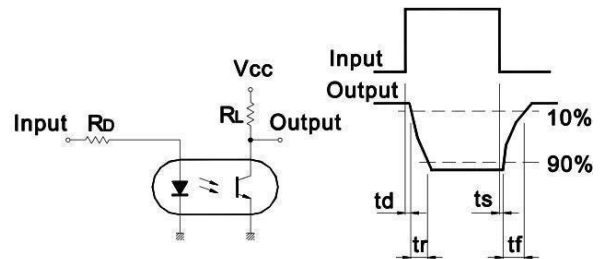


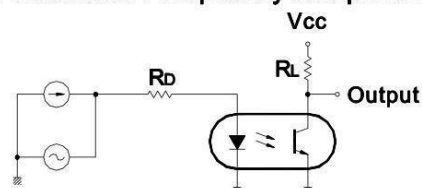
Fig.11 Frequency Response



Test Circuit for Response Time



Test Circuit for Frequency Response



15. NOTES

1. Orient is continually improving the quality, reliability, function or design and Orient reserves the right to make changes without further notices.
2. The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
3. For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
4. When requiring a device for any “specific” application, please contact our sales in advice.
5. If there are any questions about the contents of this publication, please contact us at your convenience.
6. The contents described herein are subject to change without prior notice.
7. Immerge unit’s body in solder paste is not recommended.